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a	b	c	d	e	f	g + h + i
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**06 162 FR4 35 L10.35\_41.00 P10 S1**

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

**06\_162\_FR4\_35\_L10.35\_41.00\_p10\_s1**

Layers	in $\mu$	Material	Build-Up	Assembly	
<b>Layer-1</b>	35 $\mu$	Copper		} <b>A1</b>	
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-2</b>	35 $\mu$	Copper			
	100 $\mu$	L-FR4			
<b>Layer-3</b>	35 $\mu$	Copper			
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
	410	L-FR4			
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-4</b>	35 $\mu$	Copper			} <b>A3</b>
	100 $\mu$	L-FR4			
<b>Layer-5</b>	35 $\mu$	Copper			
	100 $\mu$	Prepreg			
	100 $\mu$	Prepreg			
<b>Layer-99</b>	35 $\mu$	Copper			

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